

Glass Passivated Single-Phase Bridge Rectifiers

FEATURES

- Thin Single in-line low profile package ideal for compact required circuit
- Glass passivated junction
- High surge current capability
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC

MECHANICAL DATA

Case: KBJL

Molding compound, UL flammability classification rating 94V-0

Packing code with suffix "G" means green compound (halogen-free)

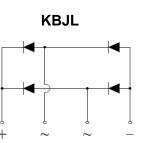
Terminal: Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 1A whisker test

Polarity: As marked

Mounting torque: 0.56 Nm max. (5 in-lbs. max.) **Weight:** 2.5g (approximately)









MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _J =25°C unless otherwise noted)					
PARAMETER	SYMBOL	TS10KL60	TS10KL80	TS10KL100	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	600	800	1000	V
Maximum RMS voltage	V _{RMS}	420	560	700	V
Maximum DC blocking voltage	V _{DC}	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	10			Α
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	180			A
Rating of fusing (t<8.3ms)	l ² t	134 A			A ² s
Maximum instantaneous forward voltage (Note 1) I_F = 5 A	V _F	1.0		V	
Maximum reverse current @ rated VR T _J =25 °C T _J =100 °C	I _R	5 150		μA	
Typical thermal resistance (Note 2)	R _{θJC}	1.5		°C/W	
Operating junction temperature range	TJ		- 55 to +150		°C
Storage temperature range	T _{STG}	- 55 to +150 °C			
Note 1: Pulse test with PW=300 us 1% duty cycle	•	-			

Note 1: Pulse test with PW=300 μ s, 1% duty cycle

Note 2: Mount on Heatsink size of 4" x 6" x 0.25" Al-Plate



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ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
TS10KLXX (Note 1)	D3	G	KBJL	20 / TUBE

Note 1: "xx" defines voltage from 600V (TS10KL60) to 1000V (TS10KL100)

EXAMPLE						
PREFERRED P/N	PREFERRED P/N PART NO. PACKING CODE		PACKING CODE SUFFIX	DESCRIPTION		
TS10KL80 D3	TS10KL80	D3				
TS10KL80 D3G	TS10KL80	D3	G	Green compound		

RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

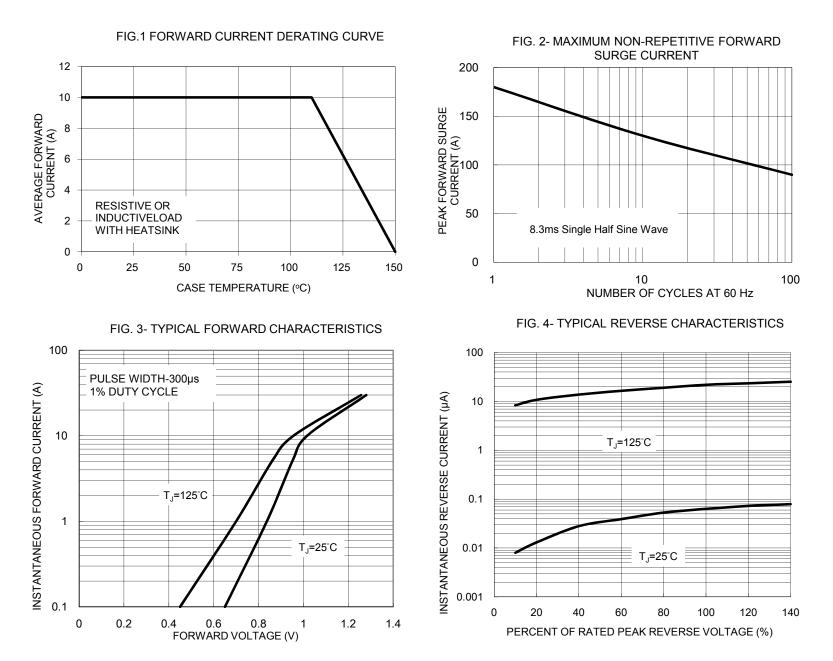
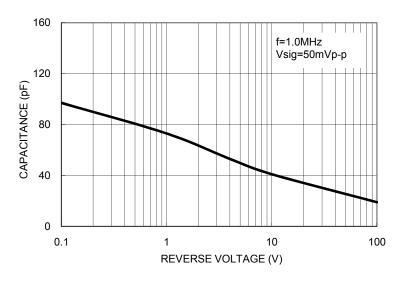


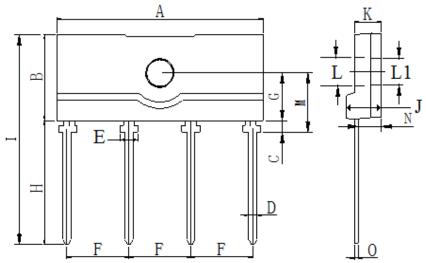


FIG. 5- TYPICAL JUNCTION CAPACITANCE



PACKAGE OUTLINE DIMENSIONS





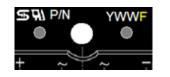
P/N

F

YWW

DIM.	Unit	(mm)	Unit (inch)		
	Min	Мах	Min	Мах	
А	24.70	25.30	0.972	0.996	
В	10.00	10.60	0.394	0.417	
С	1.20	1.60	0.047	0.063	
D	0.90	1.10	0.035	0.043	
E	2.10	2.30	0.083	0.091	
F	7.30	7.70	0.287	0.303	
G	5.50	5.90	0.217	0.232	
Н	14.40	15.40	0.567	0.606	
I	24.90	25.50	0.980	1.004	
J	4.00	4.40	0.157	0.173	
K	3.00	3.40	0.118	0.134	
L	3.30	3.50	0.130	0.138	
L1	3.10	3.30	0.122	0.130	
М	6.90	7.30	0.272	0.287	
N	2.50	2.90	0.098	0.114	
0	0.30	0.70	0.012	0.028	

MARKING DIAGRAM



= Specific Device Code

= Date Code

= Factory Code



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